Embedlet Wiring Tool

The purpose of the Embedlets Wiring Tool is to allow Embedlet applications to be graphically wired together either by programmers or by non-programmer application assemblers. The Wiring Tool will eventually have a **Specification** mode and a **Wiring Tool** mode.

In **Specification** mode the Wiring Tool is responsible for the specification of how an application is wired together using Embedlets, JAPL peripherals and protocol adapters. After the application is finished, an XML configuration file is created that represents this wiring.

In **Wiring Tool** mode the Wiring Tool will host a live Embedlet Container and as Embedlets are dragged from a pallet and dropped into the container they are instantiated and completely functional. A JAPL pallet will contain a selection of JAPL peripherals in it that can be dropped into the wiring area and then attached to the sides of the Embedlet Container as is shown in the Architecture document. These JAPL interfaces can then be implemented by simulated I/O modules which are wired to the implementation side of the JAPL peripheral or by physical PnP modules that are attached to the workstation.

As the Embedlet based application is wired together, its functionality can be continuously tested by sending live events to the Embedlets using a dialog in the Wiring Tool or by triggering the simulated JAPL I/O module or by triggering the physical I/O module. ID tags on the I/O modules can also be read or configured at this time so that when the I/O circuit is detached from the workstation and moved over to the target embedded system, the application has already had its bindings made with the I/O modules.